European Patent Office
Espacenet

Bibliographic data: JPH0521362 (A) — 1993-01-29

FORMING METHOD FOR CVD FILM

Inventor(s): MATSUKI TOMOYOSHI + (MATSUKI TOMOYOSHI)

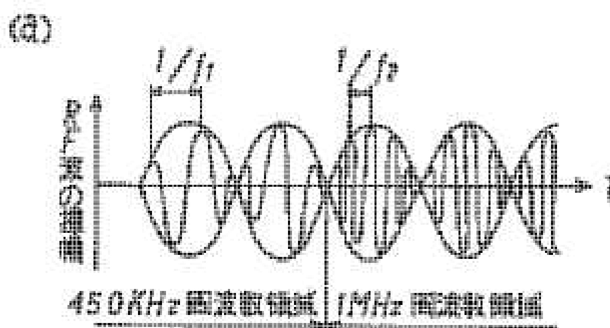
Applicant(s): MITSUBISHI ELECTRIC CORP + (MITSUBISHI ELECTRIC CORP)

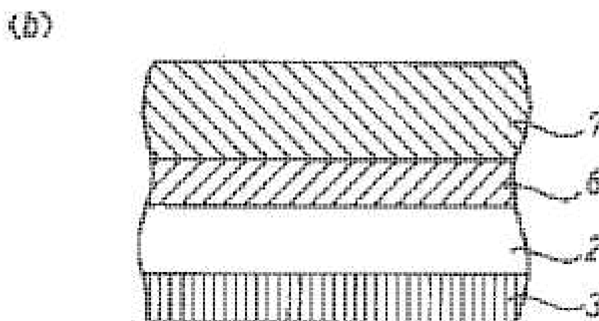
Classification: - international: ***C23C16/50; H01L21/205; H01L21/31;*** (IPC1-7): C23C16/50; H01L21/205; H01L21/31
- cooperative:

Application number: JP19910175685 19910717 Global Dossier

Priority number(s): JP19910175685 19910717

Abstract of JPH0521362 (A)





PURPOSE:To form a CVD film of desired quality with constant thickness even if an insulating film is deposited on a rear surface of a silicon wafer by switching a frequency of a high frequency signal among a plurality of stages to be controlled when the signal is applied to a plasma CVD device to form the CVD film. CONSTITUTION:When an insulating film 3 is deposited on a rear surface of a silicon wafer 2, an impedance of a holder depends upon a capacity of the insulating film and a frequency of an RF wave. A CVD film formed on the wafer 2 is necessarily a film having high quality and high denseness on a part in contact with the wafer 2, but a part which is not in contact with the wafer is not important and may hence be of low quality. The frequency of the RF wave is set to 450kHz for a relatively short time, and a CVD film 6 is formed thinly. Then, the

DOCKET ALARM
Find authenticated court documents without watermarks at docketalarm.com.

formed thickly on the film 6. Thus, the film 6 becomes a high quality and dense, and the film 7 becomes a low quality and porous.

DOCKET ALARM Find authenticated court documents without watermarks at docketalarm.com.